

## P-Channel Enhancement MOSFET

### KX6P02

#### ■ Features

- VDS (V) = -20V

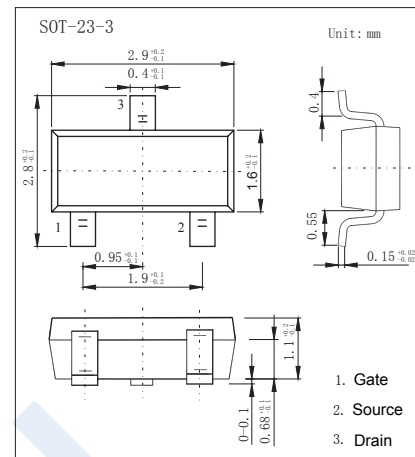
- Low ON-resistance:

$$R_{DS(ON)} = 88.4m\Omega \text{ (VGS} = -1.5V)$$

$$R_{DS(ON)} = 56m\Omega \text{ (VGS} = -1.8V)$$

$$R_{DS(ON)} = 39.7m\Omega \text{ (VGS} = -2.5V)$$

$$R_{DS(ON)} = 29.8m\Omega \text{ (VGS} = -4.5V)$$



#### ■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	-20	V
Gate-Source Voltage	V <sub>GS</sub>	±8	
Continuous Drain Current *1	I <sub>D</sub>	-6.0	A
Pulsed Drain Current *2	I <sub>DM</sub>	-24	
Power Dissipation *3	P <sub>D</sub>	1	W
Power Dissipation t=10s		2	
Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to 150	

\*1 The channel temperature should not exceed 150°C during use.

\*2 PW ≦ 10μs, Duty ≦ 1%

\*3 Mounted on a FR4 board.

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## ■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	I <sub>D</sub> = -1mA, V <sub>GS</sub> = 0V	-20			V
	V <sub>DS</sub>	I <sub>D</sub> = -1mA, V <sub>GS</sub> = 5V *1	-15			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V			-1	μA
Gate-Body leakage current	I <sub>GSS</sub>	V <sub>DS</sub> = ±8V, V <sub>GS</sub> = 0V			±1	μA
Gate Threshold Voltage	V <sub>GS(off)</sub>	V <sub>DS</sub> = -3V, I <sub>D</sub> = -1mA	-0.3		-1.0	V
Forward transfer admittance	g <sub>fs</sub>	V <sub>DS</sub> = -3V, I <sub>D</sub> = -1.0A *2	4.5	9.1		S
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3.0A *2		24.9	29.8	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -2.5A *2		31.1	39.7	
		V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -1.5A *2		38.8	56	
		V <sub>GS</sub> = -1.5V, I <sub>D</sub> = -0.5A *2		47.4	88.4	
Input Capacitance	C <sub>i ss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = -10V, f = 1MHz		840		pF
Output Capacitance	C <sub>o ss</sub>			118		
Reverse Transfer Capacitance	C <sub>r ss</sub>			99		
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> = -4.5V, V <sub>DD</sub> = -10V, I <sub>DS</sub> = -4A		12.8		nC
Gate Source Charge	Q <sub>gs</sub>			1.4		
Gate Drain Charge	Q <sub>gd</sub>			3.0		
Turn-On DelayTime	t <sub>d(on)</sub>	V <sub>GS</sub> = 0 to -2.5V, V <sub>DD</sub> = -10V, I <sub>D</sub> = -2.0A, R <sub>GEN</sub> = 4.7Ω		32		ns
Turn-Off DelayTime	t <sub>d(off)</sub>			107		
Diode Forward Voltage	V <sub>SD</sub>	I <sub>D</sub> = 6.0A, V <sub>GS</sub> = 0V		0.87	1.2	V

\*1 VDSX mode (the application of a plus voltage between gate and source) may cause decrease in maximum rating of drain-source voltage

\*2 Pulse test

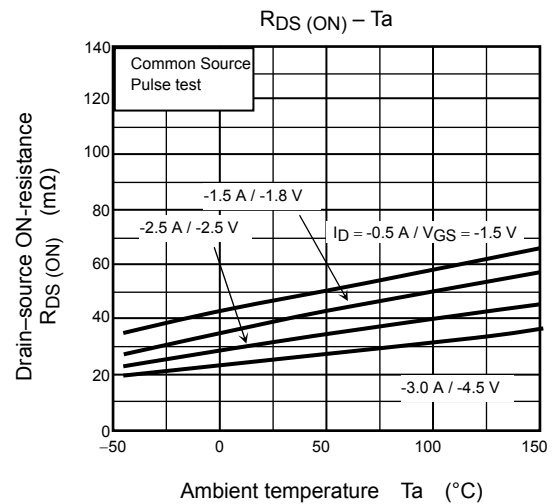
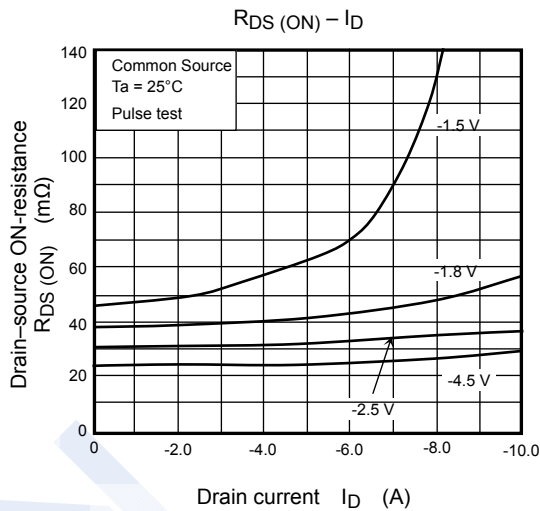
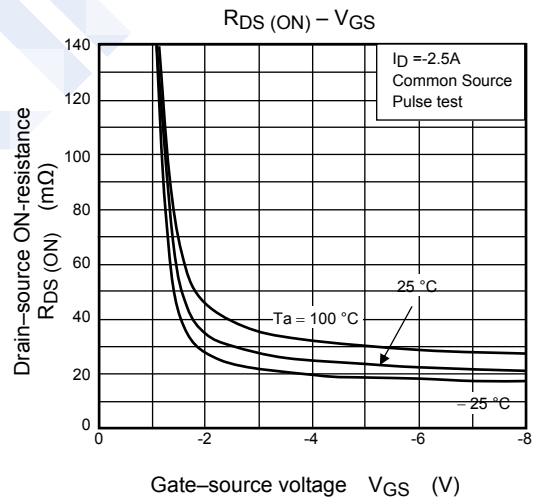
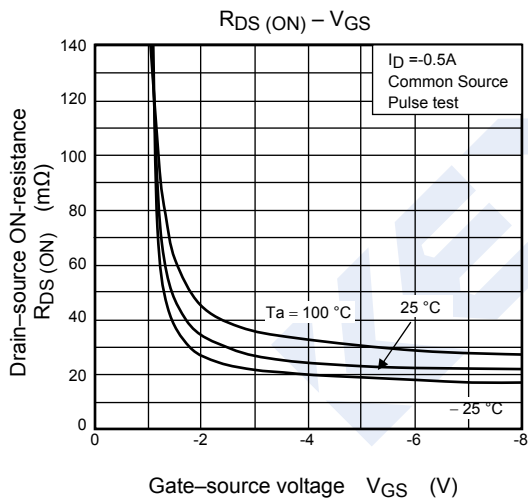
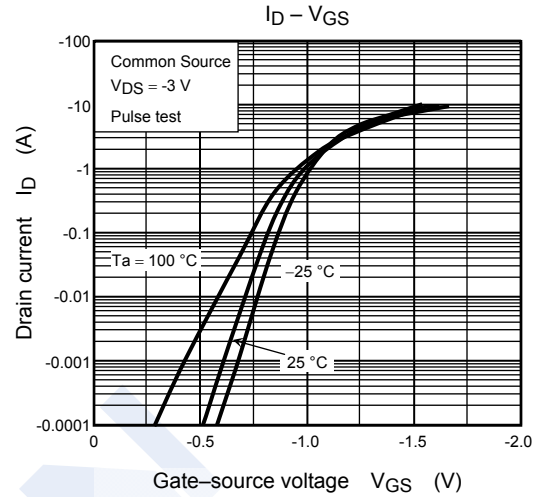
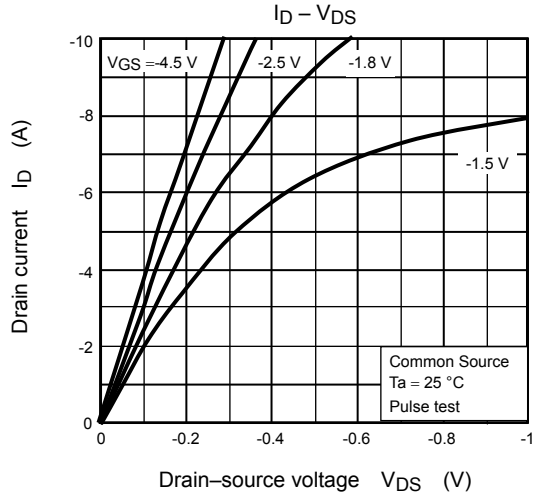
## ■ Marking

Marking	KFH
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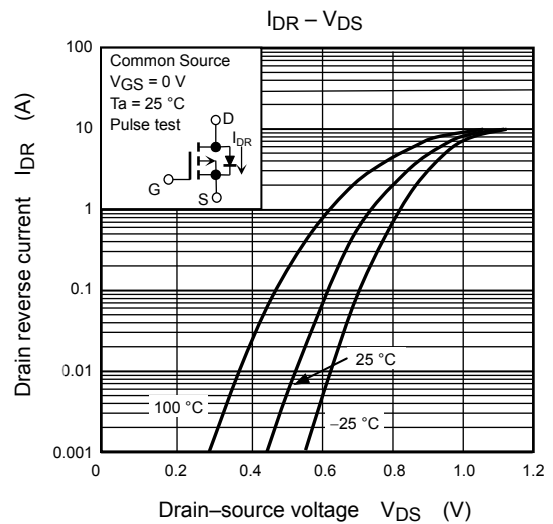
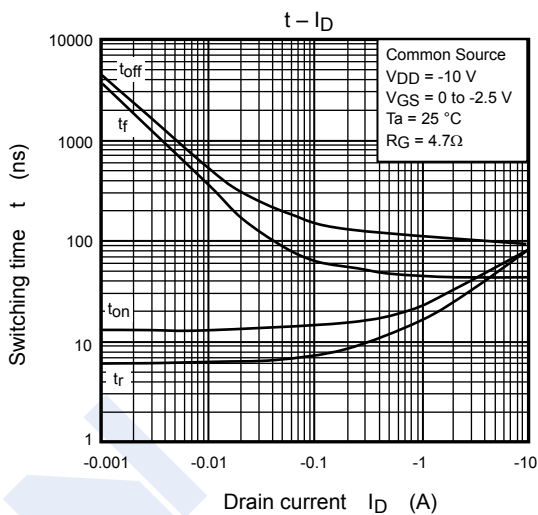
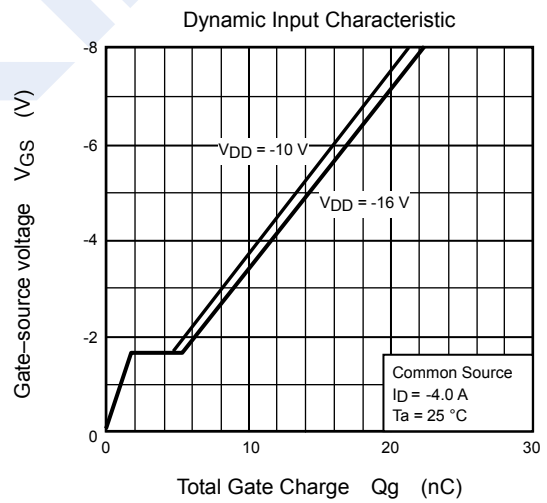
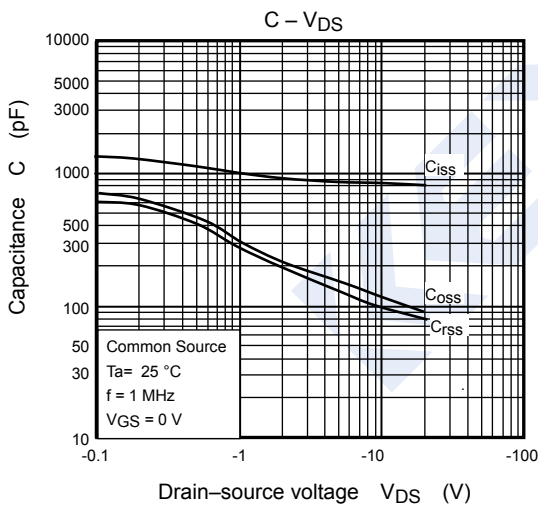
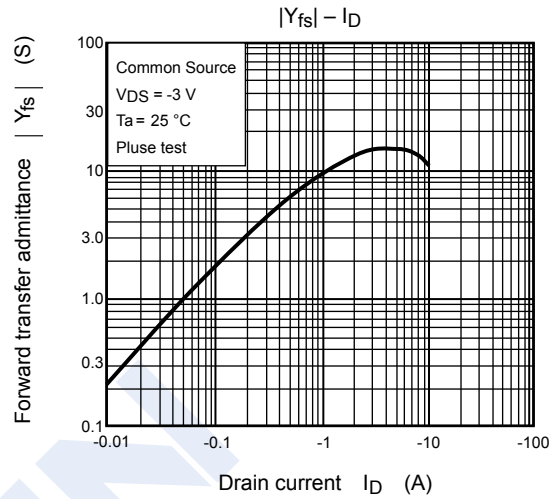
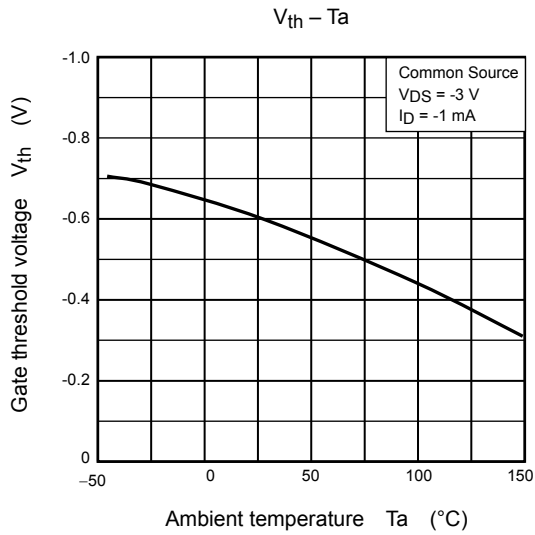
### Typical Characteristics



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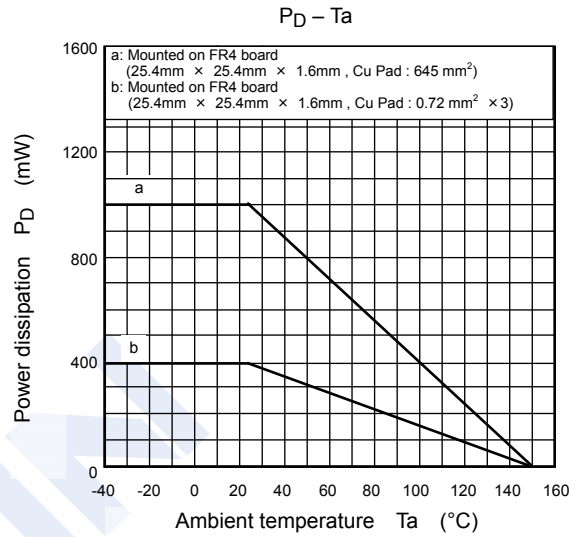
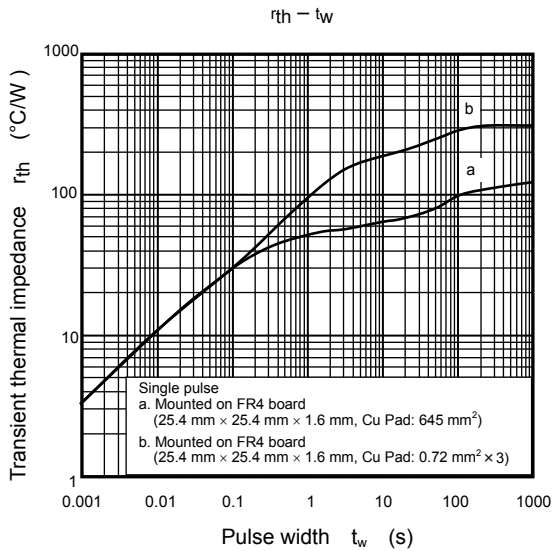
### Typical Characteristics



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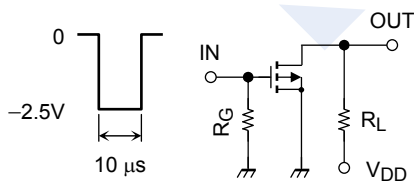
#### Typical Characteristics



#### Typical Application

#### Switching Time Test Circuit

##### (a) Test Circuit



$V_{DD} = -10\text{ V}$   
 $R_G = 4.7\ \Omega$   
 Duty.  $\leq 1\%$   
 $V_{IN}$ :  $t_r, t_f < 5\text{ ns}$   
 Common Source  
 $T_a = 25^{\circ}\text{C}$

##### (b) $V_{IN}$



##### (c) $V_{OUT}$

